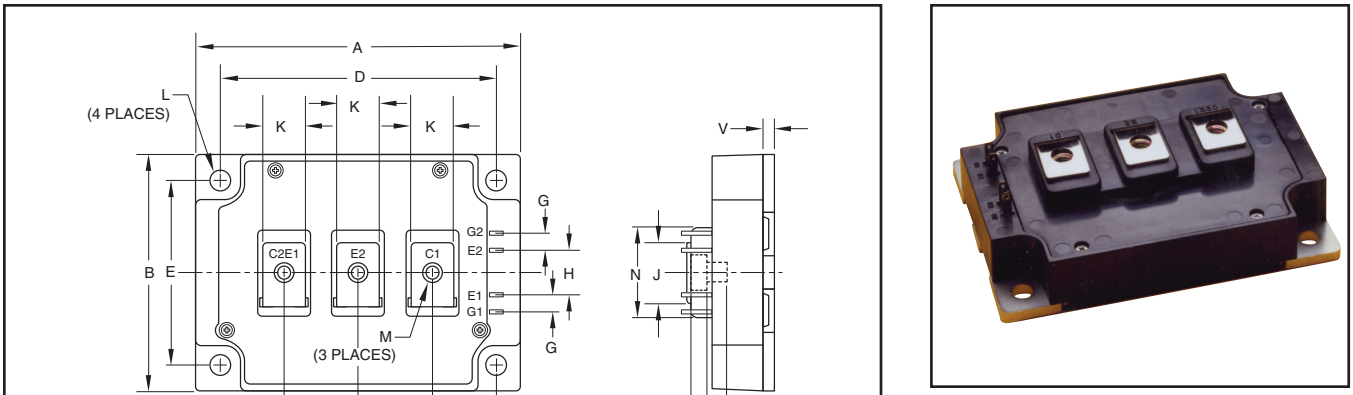
Powerex, Inc., 173 Pavilion Lane, Youngwood, Pennsylvania 15697 (724) 925-7272
www.pwrx.com

CM450DY-24S

Dual IGBTMOD™ S-Series Module
450 Amperes/1200 Volts



Tolerance Otherwise Specified

Division of Dimension	Tolerance
0.5 to 3	±0.2
over 3 to 6	±0.3
over 6 to 30	±0.5
over 30 to 120	±0.8
over 120 to 400	±1.2

Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.15	80.0
C	1.14+0.04/-0.02	29.0+1.0/-0.5
D	3.66±0.01	93.0±0.25
E	2.44±0.01	62.0±0.25
F	0.98	25.0
G	0.24	6.0
H	0.59	15.0
J	0.81	20.5
K	0.55	14.0
L	0.26 Dia.	Dia. 6.5
M	M6 Metric	M6

Dimensions	Inches	Millimeters
N	1.18	30.0
P	0.71	18.0
Q	0.28	7.0
R	0.83	21.2
S	0.33	8.5
T	0.0157	0.4
U	0.110	2.8
V	0.16	4.0
W	0.30	7.5
X	0.21	5.3
Y	0.47	12.0
Z	0.85	21.5

Description:
Powerex Dual IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:
- ☐ Low Drive Power
- ☐ Low $V_{CE(sat)}$
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:
- ☐ AC Motor Control
- ☐ Motion/Servo Control
- ☐ UPS
- ☐ Welding Power Supplies
- ☐ Laser Power Supplies

Ordering Information:
Example: Select the complete module number you desire from the table - i.e. CM450DY-24S is a 1200V (V_{CES}), 450 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	450	24

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Absolute Maximum Ratings, T_j = 25°C unless otherwise specified

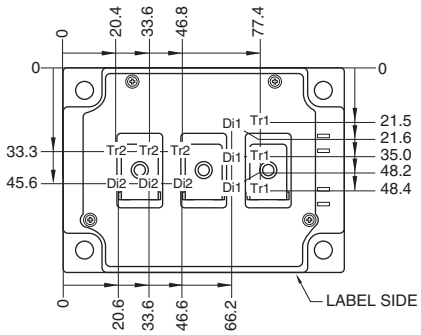
Inverter Part IGBT/FWDi

Characteristics	Symbol	Rating	Units
Collector-Emitter Voltage (V_{GE} = 0V)	V_{CES}	1200	Volts
Gate-Emitter Voltage (V_{CE} = 0V)	V_{GES}	±20	Volts
Collector Current (DC, T_C = 125°C)*2,*8	I_C	410	Amperes
Collector Current (Pulse, Repetitive)*3	I_{CRM}	900	Amperes
Total Power Dissipation (T_C = 25°C)*2,*4	P_{tot}	3330	Watts
Emitter Current (T_C = 25°C)*2,*4,*8	I_E*1	410	Amperes
Emitter Current (Pulse, Repetitive)*3	I_{ERM}*1	900	Amperes

Module

Characteristics	Symbol	Rating	Units
Maximum Junction Temperature	$T_{j(max)}$	+175	°C
Operating Junction Temperature	$T_{j(op)}$	-40 to +150	°C
Storage Temperature	T_{stg}	-40 to +125	°C
Case Temperature,*2	T_C	-40 to +125	°C
Isolation Voltage (Terminals to Baseplate, RMS, f = 60Hz, AC 1 minute)	V_{ISO}	2500	Volts

*1 Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWDi).
*2 Case temperature (T_C) and heatsink temperature (T_s) is measured on the surface (mounting side) of the baseplate and the heatsink side just under the chips. Refer to the figure to the right for chip location. The heatsink thermal resistance should be measured just under the chips.
*3 Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.
*4 Junction temperature (T_j) should not increase beyond maximum junction temperature ($T_{j(max)}$) rating.
*8 This model has 450A size IGBT and FWDi chips. This package limitation is based on package issue.



Tr1 / Tr2: IGBT, Di1 / Di2: FWDi
Each mark points to the center position of each chip.

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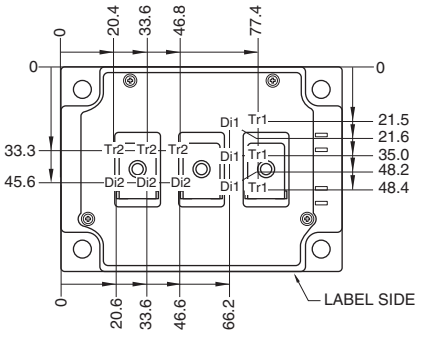
Electrical Characteristics, T_j = 25°C unless otherwise specified

Inverter Part IGBT/FWDi

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Emitter Cutoff Current	I_{CES}	$V_{CE} = V_{CES}$, V_{GE} = 0V	—	—	1	mA
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = V_{GES}$, V_{CE} = 0V	—	—	0.5	µA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	I_C = 45mA, V_{CE} = 10V	5.4	6	6.6	Volts
Collector-Emitter Saturation Voltage (Terminal)	$V_{CE(sat)}$	I_C = 450A, V_{GE} = 15V, T_j = 25°C*5	—	1.80	2.25	Volts
		I_C = 450A, V_{GE} = 15V, T_j = 125°C*5	—	2.05	—	Volts
		I_C = 450A, V_{GE} = 15V, T_j = 150°C*5	—	2.10	—	Volts
Collector-Emitter Saturation Voltage (Chip)	$V_{CE(sat)}$	I_C = 450A, V_{GE} = 15V, T_j = 25°C*5	—	1.70	2.15	Volts
		I_C = 450A, V_{GE} = 15V, T_j = 125°C*5	—	1.90	—	Volts
		I_C = 450A, V_{GE} = 15V, T_j = 150°C*5	—	1.95	—	Volts
Input Capacitance	C_{ies}	V_{CE} = 10V, V_{GE} = 0V	—	—	45	nF
Output Capacitance	C_{oes}		—	—	9.0	nF
Reverse Transfer Capacitance	C_{res}		—	—	0.75	nF
Gate Charge	Q_G	V_{CC} = 600V, I_C = 450A, V_{GE} = 15V	—	1050	—	nC
Turn-on Delay Time	$t_{d(on)}$	V_{CC} = 600V, I_C = 450A, V_{GE} = ±15V, R_G = 0Ω, Inductive Load	—	—	800	ns
Rise Time	t_r		—	—	200	ns
Turn-off Delay Time	$t_{d(off)}$		—	—	600	ns
Fall Time	t_f		—	—	300	ns
Emitter-Collector Voltage (Terminal)	V_{EC}*1	I_E = 450A, V_{GE} = 0V, T_j = 25°C*5	—	1.85	2.30	Volts
		I_E = 450A, V_{GE} = 0V, T_j = 125°C*5	—	1.85	—	Volts
		I_E = 450A, V_{GE} = 0V, T_j = 150°C*5	—	1.85	—	Volts
Emitter-Collector Voltage (Chip)	V_{EC}*1	I_E = 450A, V_{GE} = 0V, T_j = 25°C*5	—	1.70	2.15	Volts
		I_E = 450A, V_{GE} = 0V, T_j = 125°C*5	—	1.70	—	Volts
		I_E = 450A, V_{GE} = 0V, T_j = 150°C*5	—	1.70	—	Volts
Reverse Recovery Time	t_{rr}*1	V_{CC} = 600V, I_E = 450A, V_{GE} = ±15V	—	—	300	ns
Reverse Recovery Charge	Q_{rr}*1	R_G = 0Ω, Inductive Load	—	24	—	µC
Turn-on Switching Energy per Pulse	E_{on}	V_{CC} = 600V, I_C = I_E = 450A, V_{GE} = ±15V, R_G = 0Ω, T_j = 150°C, Inductive Load	—	54.9	—	mJ
Turn-off Switching Energy per Pulse	E_{off}		—	48.0	—	mJ
Reverse Recovery Energy per Pulse	E_{rr}*1		—	32.4	—	mJ
Internal Lead Resistance	$R_{CC' + EE'}$	Main Terminals-Chip, Per Switch, T_C = 25°C*2	—	—	0.7	mΩ
Internal Gate Resistance	r_g	Per Switch	—	4.3	—	Ω

*1 Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWDi).
*2 Case temperature (T_C) and heatsink temperature (T_s) is measured on the surface (mounting side) of the baseplate and the heatsink side just under the chips. Refer to the figure to the right for chip location. The heatsink thermal resistance should be measured just under the chips.
*5 Pulse width and repetition rate should be such as to cause negligible temperature rise.



Tr1 / Tr2: IGBT, Di1 / Di2: FWDi
Each mark points to the center position of each chip.

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Thermal Resistance Characteristics, T_j = 25°C unless otherwise specified

Thermal Resistance, Junction to Case*2	$R_{th(j-c)}Q$	Per Inverter IGBT	—	—	0.045	K/W
Thermal Resistance, Junction to Case*2	$R_{th(j-c)}D$	Per Inverter FWDi	—	—	0.068	K/W
Contact Thermal Resistance, Case to Heatsink*2	$R_{th(c-f)}$	Thermal Grease Applied (Per 1 Module)*6	—	0.018	—	K/W

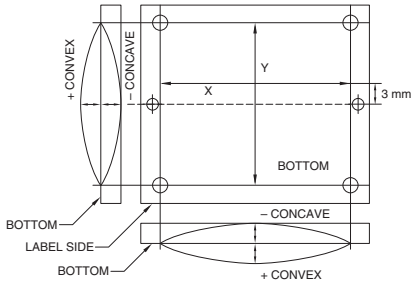
Mechanical Characteristics

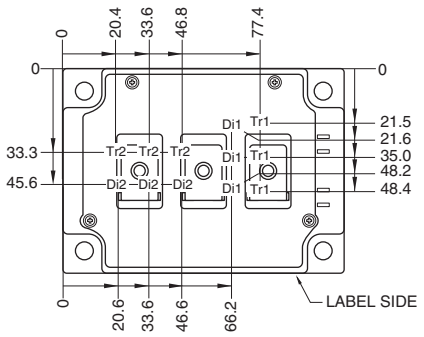
Mounting Torque	M_t	Main Terminals, M6 Screw	31	35	40	in-lb
	M_s	Mounting to Heatsink, M6 Screw	31	35	40	in-lb
Creepage Distance	d_s	Terminal to Terminal	—	—	—	mm
		Terminal to Baseplate	—	—	—	mm
Clearance	d_a	Terminal to Terminal	—	—	—	mm
		Terminal to Baseplate	—	—	—	mm
Weight	m		—	580	—	Grams
Flatness of Baseplate	e_c	On Centerline X, Y*7	-100	—	±100	µm

Recommended Operating Conditons, T_a = 25°C

(DC) Supply Voltage	V_{CC}	Applied Across C1-E2	—	600	850	Volts
Gate (-Emitter Drive) Voltage	$V_{GE(on)}$	Applied Across G1-Es1 / G2-Es2	13.5	15.0	16.5	Volts
External Gate Resistance	R_G	Per Switch	0	—	8	Ω

*2 Case temperature (T_C) and heatsink temperature (T_s) is measured on the surface (mounting side) of the baseplate and the heatsink side just under the chips.
Refer to the figure to the right for chip location.
The heatsink thermal resistance should be measured just under the chips.
*6 Typical value is measured by using thermally conductive grease of λ = 0.9 [W/(m • K)].
*7 Baseplate (mounting side) flatness measurement points (X, Y) are shown in the figure below.





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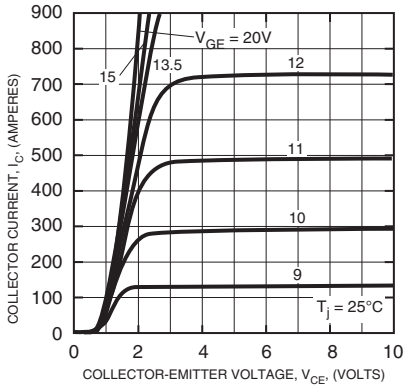
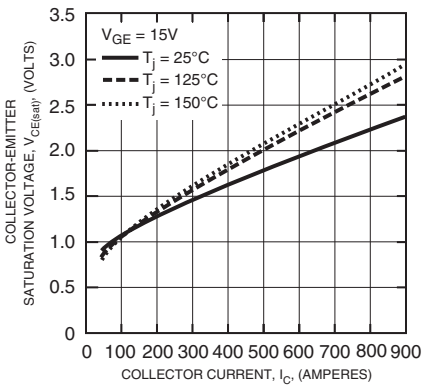
OUTPUT CHARACTERISTICS (CHIP - TYPICAL)



COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (CHIP - TYPICAL)



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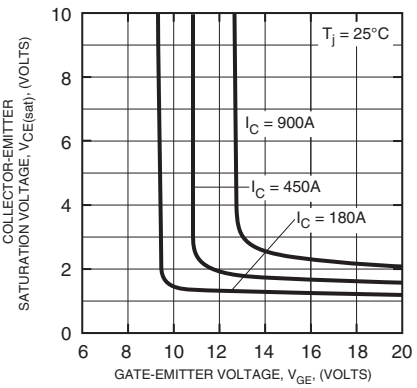
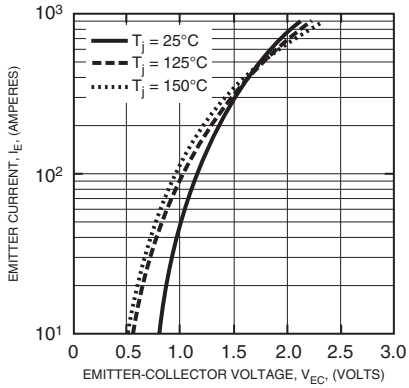
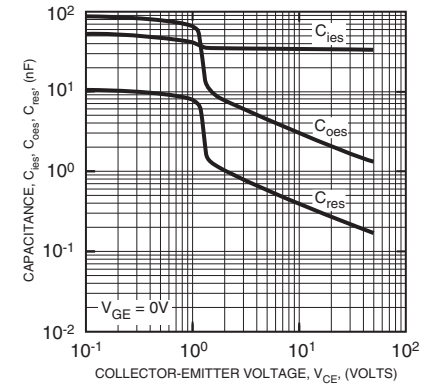


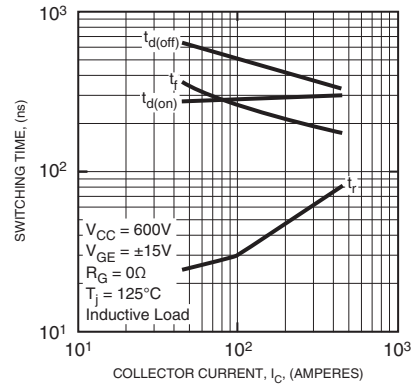
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (CHIP - TYPICAL)



CAPACITANCE VS. V_{CE} (TYPICAL)



HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



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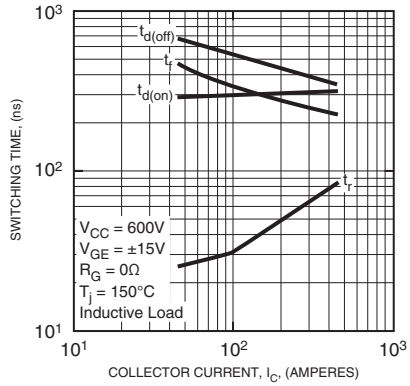
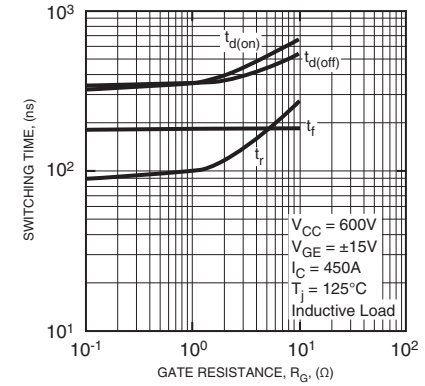


SWITCHING TIME VS. GATE RESISTANCE (TYPICAL)



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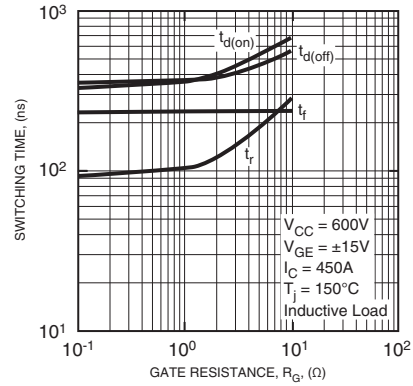

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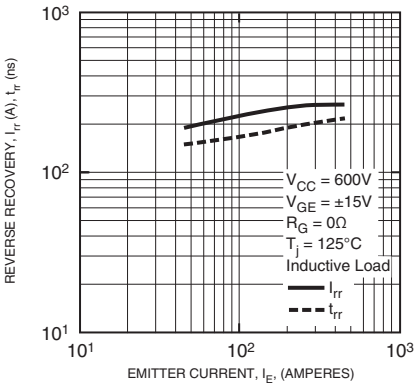
REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



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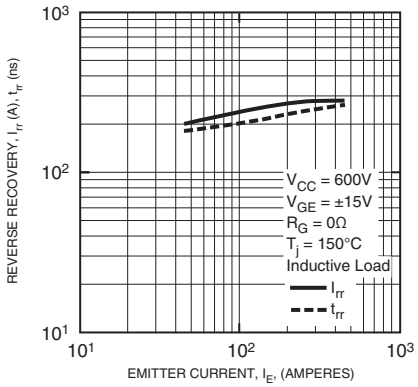
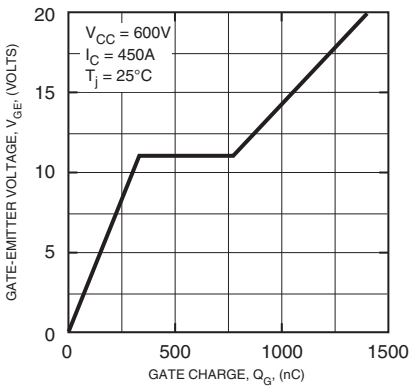
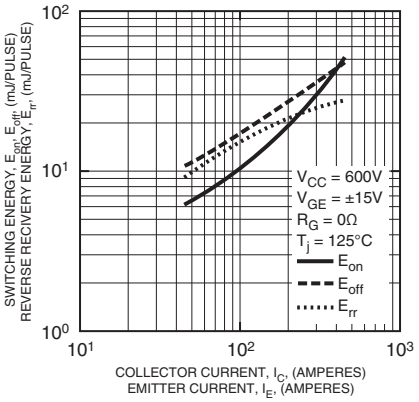


GATE CHARGE VS. V_{GE}



HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



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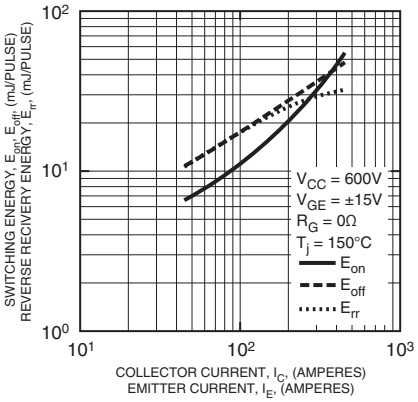

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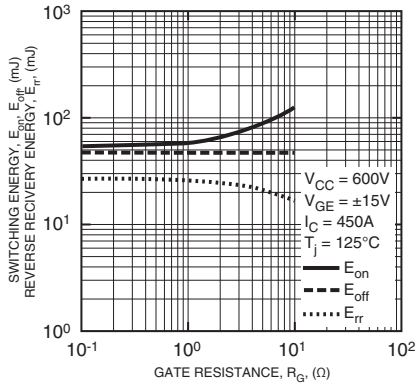

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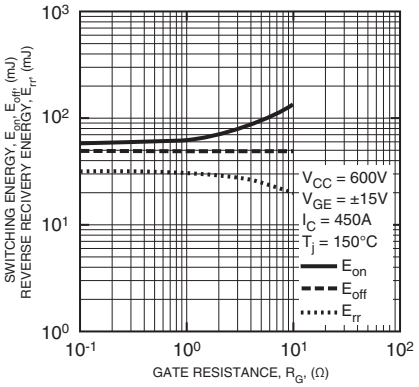

TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (MAXIMUM)